

DFN1006-2L Plastic-Encapsulate ESD Protection Diodes

Features

- Low leakage current
- DFN1006 surface mount package
- IEC 61000-4-2 (ESD Air): ±15kV
- IEC 61000-4-2 (ESD Contact): ±8kV
- IEC 61000-4-5 (Lightning 8/20μs): 2.5A

Applications

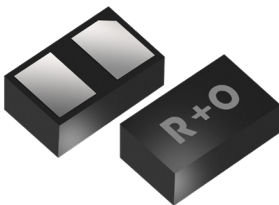
- Cellular Handsets and Accessories
- Notebooks and Handhelds, Audio Players, Peripherals
- Personal Digital Assistants, Portable
- Keypads, Side Keys, LCD Displays

Function Diagram



Reverse Working Voltage
15V Max.
Ultra Small capacitance
0.5pF(Max.)

DFN1006-2L

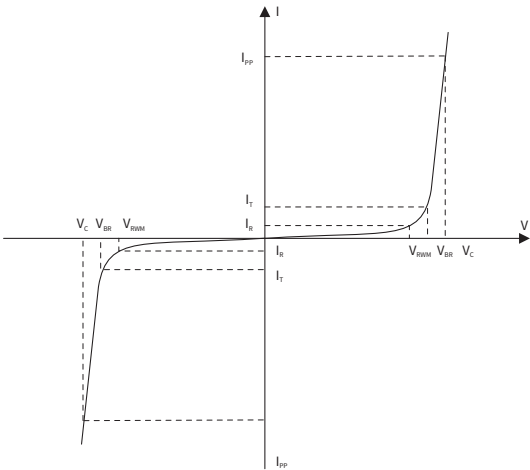


Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	±15	KV
		ESD per IEC 61000-4-2(Contact)	±8.0	KV
P _{PP}	Peak Pulse Power	tp = 8/20 μs	90	W
I _{PP}	Rated Peak Pulse Current	tp = 8/20 μs	2.5	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{STG}	Operating JunctionTemperature Range	—	-55 to +150	°C

Electrical Parameter

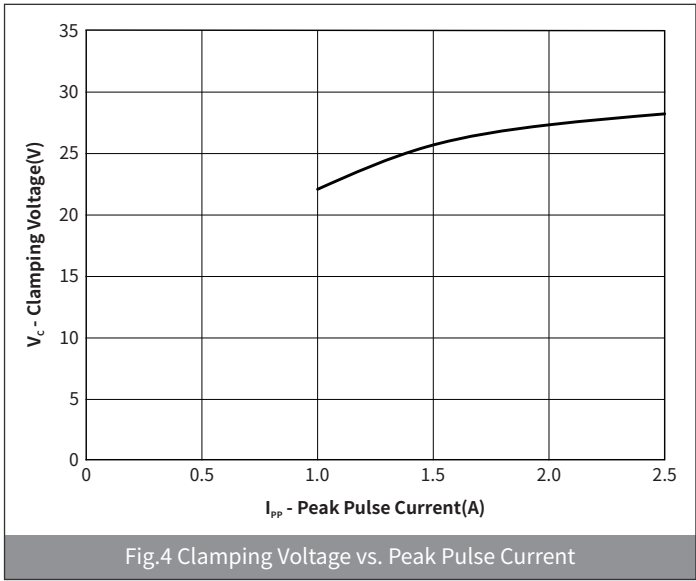
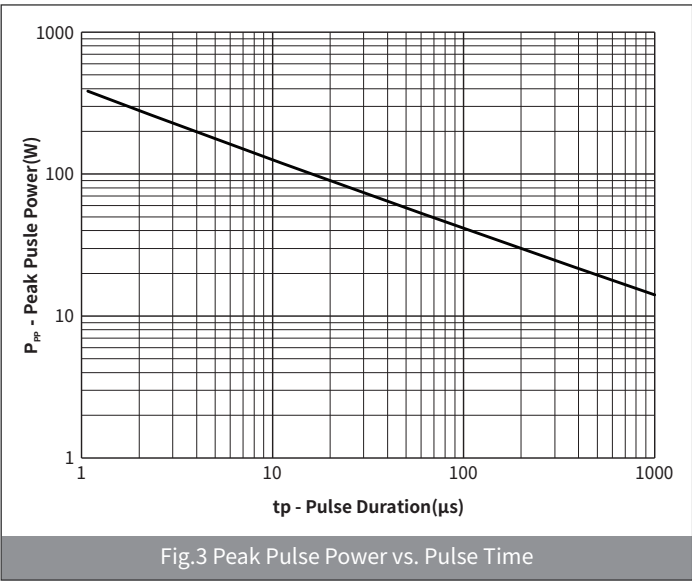
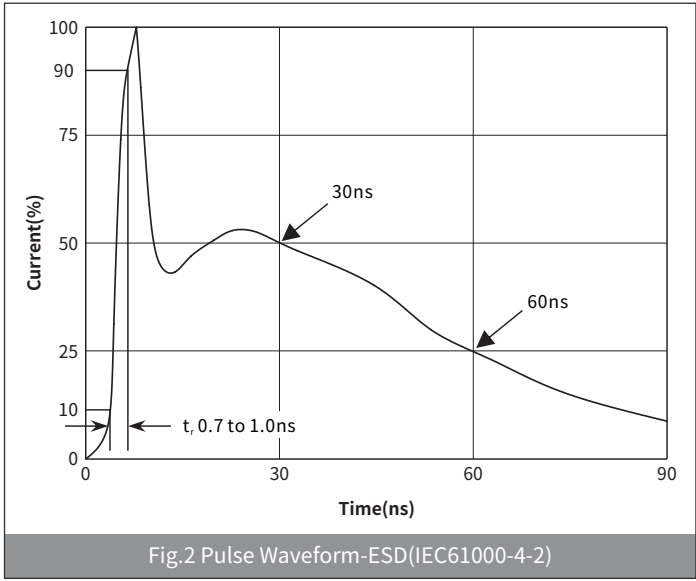
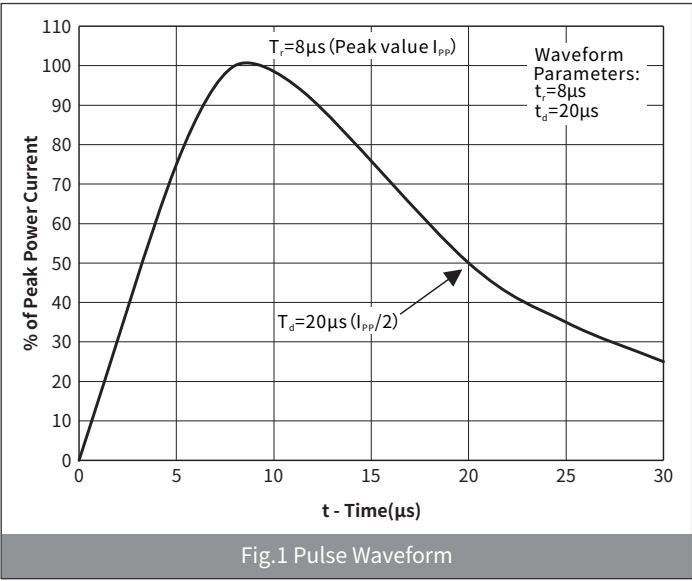
SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{PP}
V _{BR}	Breakdown Voltage @ I _T
I _{PP}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ VRWM
V _{RWM}	Peak Reverse Working Voltage
P _{PP}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz
I _F	Forward Current
V _F	Forward Voltage @I _F



● Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_a=25^{\circ}C$	—	—	15	V
Breakdown Voltage	V_{BR}	$I_R=1.0mA, T_a=25^{\circ}C$	16.7	—	21.5	V
Reverse Leakage Current	I_R	$V_R=15V, T_a=25^{\circ}C$	—	—	0.2	μA
Clamping Voltage	V_C	$I_{PP}=1.0A, t_p=8/20\mu s$	—	—	26	V
		$I_{PP}=2.5A, t_p=8/20\mu s$	—	—	35	
Junction Capacitance	C_J	$V_R=0V, f=1MHz$	—	0.3	0.5	pF

● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



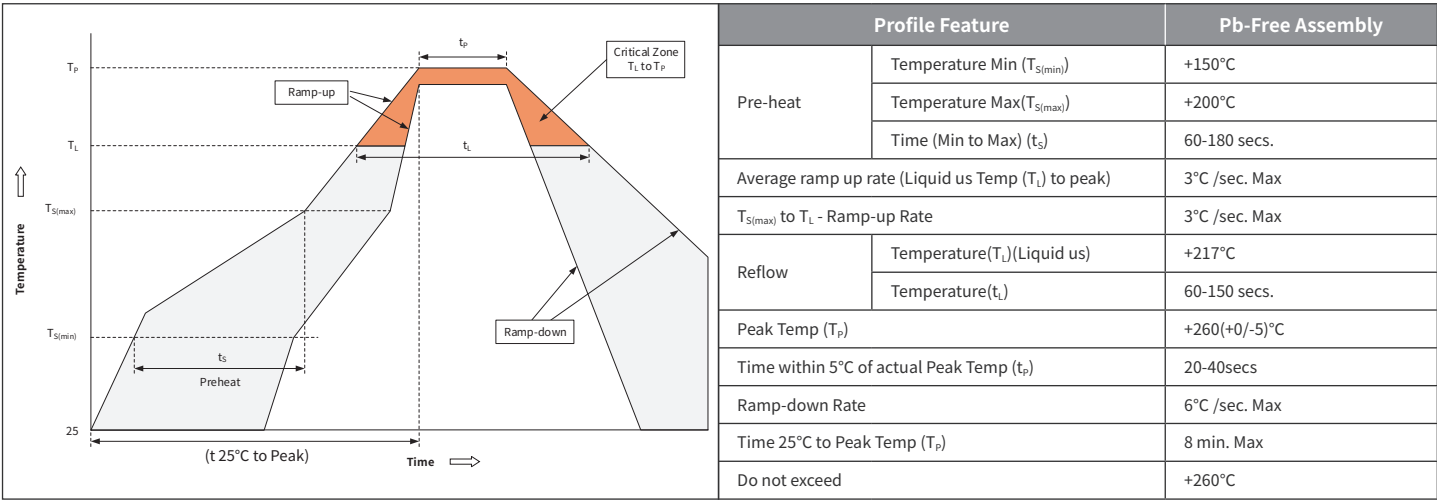
H15VU10B

Bi-directional 15V Ultra Small Capacitance ESD

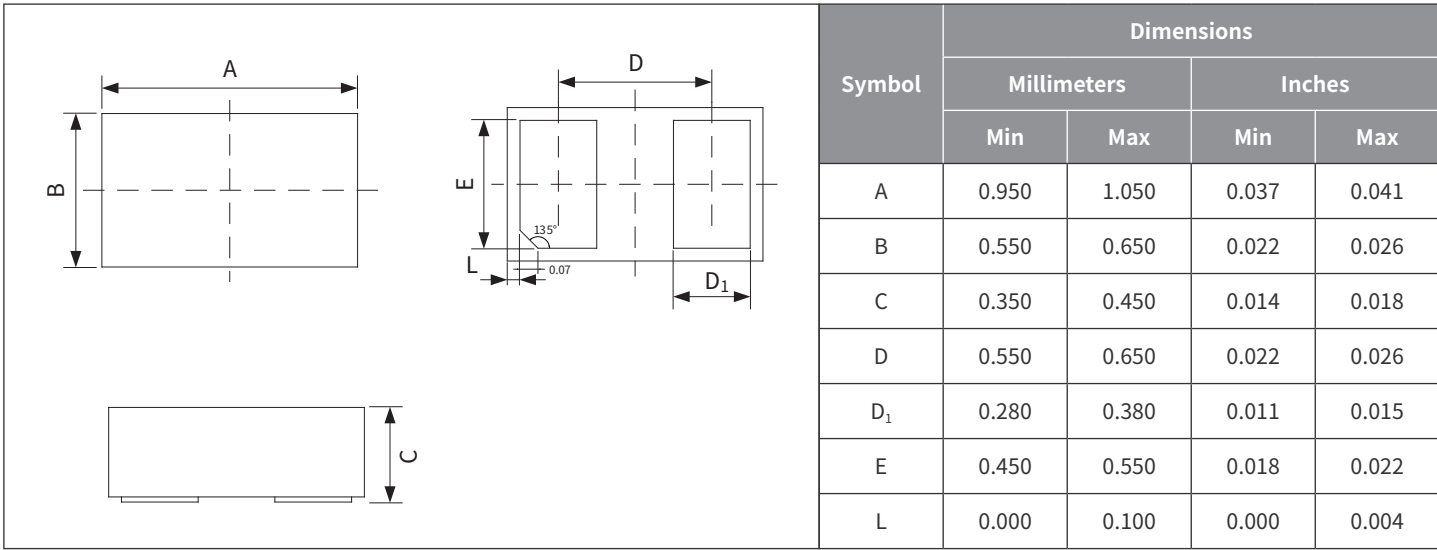
● Ordering Information

PREFERED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
H15VU10B	DFN1006-2L	1.00×0.60×0.37	7"	3000

● Recommended Soldering Conditions



● Package Outline Dimensions (DFN1006-2L)



● Suggested Pad Layout

